

# N-Channel 150 V (D-S) MOSFET

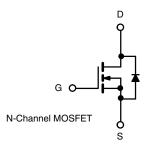
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	150			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.075			
I <sub>D</sub> (A)	20			
Configuration	Single			
Package	TO-220			

#### **FEATURES**

- TrenchFET® power MOSFET
- Package with low thermal resistance
- $\bullet$  100 %  $R_g$  and UIS tested







<b>ABSOLUTE MAXIMUM RATING</b>	<b>S</b> (T <sub>C</sub> = 25 °C, unless	otherwise noted	i)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	150	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	20	A	
	T <sub>C</sub> = 125 °C		14		
Continuous Source Current (Diode Conducti	on) <sup>a</sup>	I <sub>S</sub>	50		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	60		
Single Pulse Avalanche Energy	J 0.1 ml J	I <sub>AS</sub>	30		
Single Pulse Avalanche Current	L = 0.1 mH	E <sub>AS</sub>	45	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	107	W	
	T <sub>C</sub> = 125 °C	l LD	35		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-Ambient	PCB Mount c	$R_{thJA}$	50	°C/W		
Junction-to-Case (Drain)		$R_{thJC}$	1.4	C/VV		

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	1							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		150	-	-	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	-	3.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 150 V	-	-	1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 150 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 150 V, T <sub>J</sub> = 175 °C	-	-	250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A	- 0.075 -		-		
Drain-Source On-State Resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A, T <sub>J</sub> = 125 °C	-	0.116	-	Ω	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A, T <sub>J</sub> = 175 °C	-	0.158	-		
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub>	V <sub>DS</sub> = 12 V, I <sub>D</sub> = 15 A		33	-	S	
Dynamic <sup>b</sup>								
Input Capacitance	C <sub>iss</sub>			-	1090	1660		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{GS} = 0 \text{ V}$ $V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		165	200	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	82	120		
Total Gate Charge c	Qg			-	27	50		
Gate-Source Charge c	$Q_{gs}$	$V_{GS} = 10 \text{ V}$	$V_{DS} = 75 \text{ V}, I_{D} = 20 \text{ A}$	-	7.5	-	nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			-	10.2	-		
Gate Resistance	$R_g$		f = 1 MHz		1.0	3.2	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	11	17		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 75 V, $R_L$ = 3 $\Omega$ $I_D$ $\cong$ 20A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		-	21	33	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	20	30		
Fall Time <sup>c</sup>	t <sub>f</sub>			-	12	20		
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	65	Α	
Forward Voltage	$V_{SD}$	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		-	0.85	1.5	V	

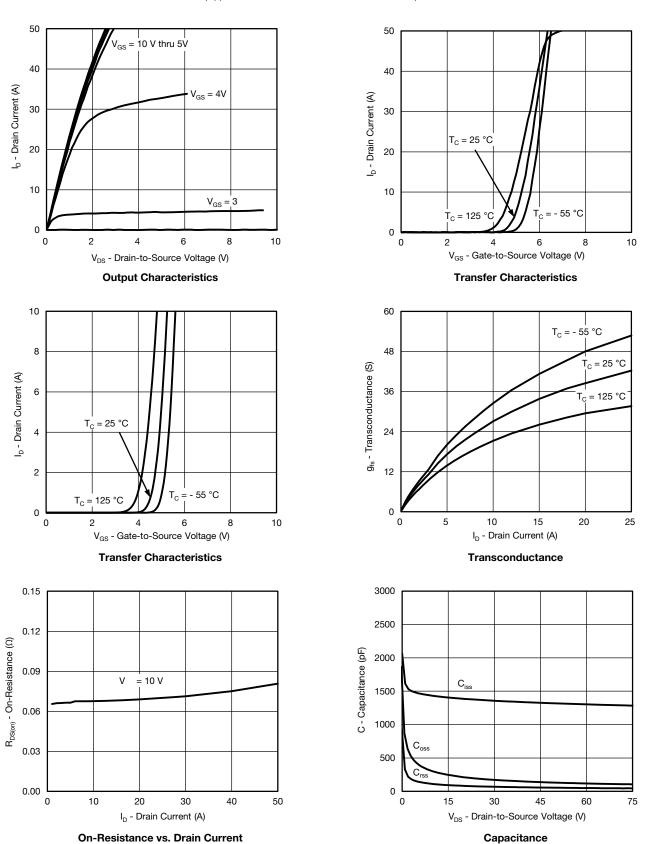
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

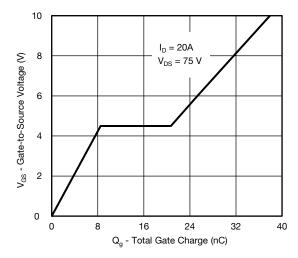


## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)

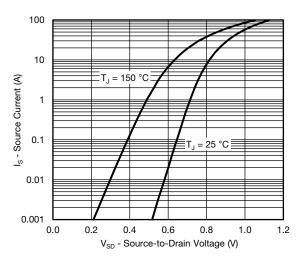




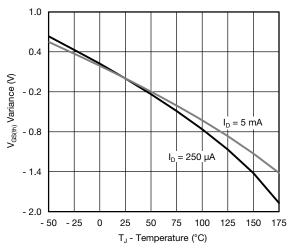
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



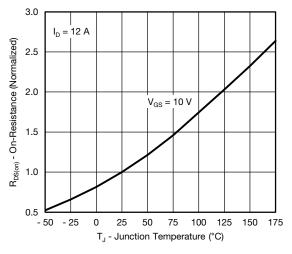
**Gate Charge** 



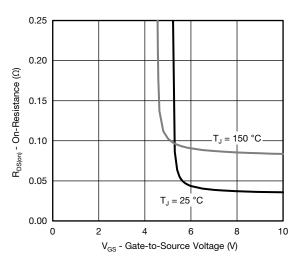
**Source Drain Diode Forward Voltage** 



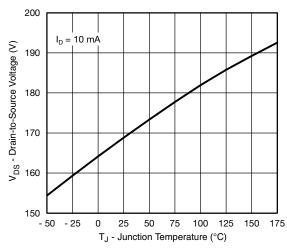
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



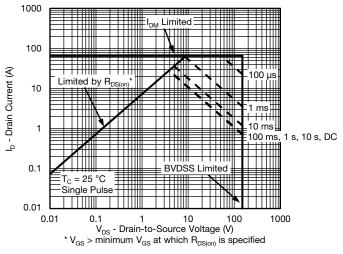
On-Resistance vs. Gate-to-Source Voltage



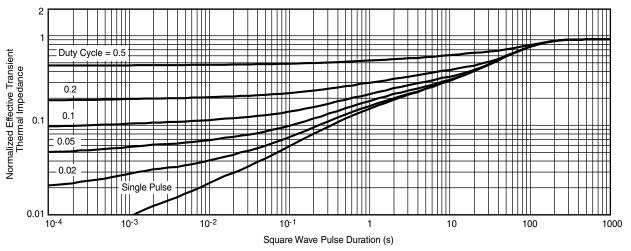
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



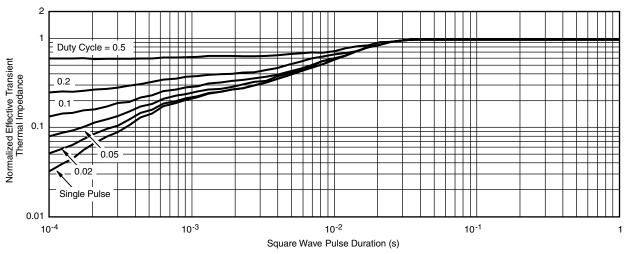
**Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

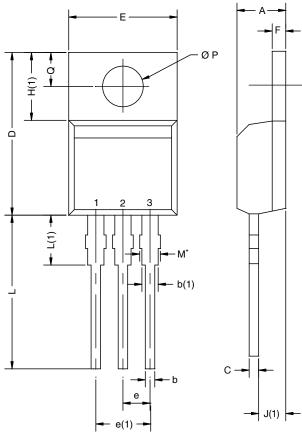
#### Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



# **TO-220AB**



'		 
		D2

	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

#### Note

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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